Overview

HP ZBook Power 15.6 inch G8 Mobile Workstation PC



- 1. Ambient Light Sensor
- 2. Internal Microphones (optional)
- 3. Camera LEDs (optional)
- 4. Camera (optional)
- 5. IR Camera (optional)
- 6. Camera Cover
- 7 Speakers
- 8. Function Keys (changes with configured options)
- 9. Power button
- 10. HP Programmable Key

Right

- 11. Numeric Keypad
- 12. Fingerprint Sensor (optional)
- 13. Touchpad
- 14. Indicator LEDs: Power light, Wireless light, Storage usage light
- 15. Power connector
- 16. USB Type-C[®] with Thunderbolt[™] 4
- 17. USB 3.1 Gen 1
- 18. USB 3.1 Gen 1
- 19. Audio Combo Jack



Overview



Left

- 1. Nano Security lock slot
- 2. RJ-45
- 3. USB 3.1 Gen 1 Charging Port

- 4. HDMI port
- 5. Smart Card Reader



Overview

At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro and HP's collaboration and connectivity technology.
- NVIDIA Quadro GPUs provide the interactive visual workspace you need to do great work wherever, whenever. With twice
 the CUDA cores as previous generations, NVIDIA Quadro GPUs deliver the performance professionals need to work from
 anywhere.
- Take multitasking to the next level with 11th gen Intel[®] Core[™] i9 processors built to handle multithreaded apps like Adobe Premiere Pro[®], and with fast clock speeds to boost your speed on single threaded apps like Autodesk 3ds Max.
- Strenuously tested to meet ISV certification and deliver superb performance and support with leading software providers, including Autodesk and Adobe[®].
- Have confidence with HP's most secure mobile workstations and defend against firmware and malware attacks with HP Sure Start and Sure Sense.
- Built with the environment in mind, this ZBook includes recycled ocean-bound plastics, plastic-free packaging, and ultraefficient power consumption.
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt[™] Dock for lightning fast Thunderbolt[™] 4 transfers and the flexibility to run up to 1 external 4K and 1 external 5K.
- Work without limits in any location with up to 4TB of local PCIe storage.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

OPERATING SYSTEM

Preinstalled OS	Windows 11 Pro ² - HP recommends Windows 11 Pro ² Windows 11 Pro Education ² Windows 11 Home - HP recommends Windows 11 Pro for business ² Windows 11 Home Single Language - HP recommends Windows 11 Pro for business ² Windows 11 Pro (Windows 11 Enterprise available with a Volume Licensing Agreement) ² Windows 10 Pro ^{1,2} Windows 10 Pro Education ^{1,2} Windows 10 Home - HP recommends Windows 11 Pro for business ^{1,2} Windows 10 Home Single Language - HP recommends Windows 11 Pro for business ^{1,2} Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement) ^{1,2} FreeDOS
Web support OS	Windows 10 Enterprise 64 ²
Supported Version	HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282

¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

PROCESSOR

11th Generation Intel[®] Core[™] i9-11950H vPro[™] with Intel[®] Iris[®] Xe Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel[®] Turbo Boost Technology, X MB cache, 8 cores) ^{1,2,3,4,5,6}

11th Generation Intel[®] Core[™] i9-11900H with Intel[®] Iris[®] Xe Graphics (2.5 GHz base frequency, up to 4.9 GHz with Intel[®] Turbo Boost Technology, X MB cache, 8 cores) ^{1,2,3,4,5,6}

11th Generation Intel[®] Core[™] i7-11850H vPro[™] with Intel[®] Iris[®] Xe Graphics (2.5 GHz base frequency, up to 4.8 GHz with Intel[®] Turbo Boost Technology, X MB cache, 8 cores) ^{1,2,3,4,5,6}

11th Generation Intel[®] Core[™] i7 11800H with Intel[®] Iris[®] Xe Graphics (2.3 GHz base frequency, up to 4.6 GHz with Intel[®] Turbo Boost Technology, X MB cache, 8 cores)^{1,2,3,4,5}

11th Generation Intel[®] Core™ i5-11500H vPro™ with Intel[®] Iris[®] Xe Graphics (2.9 GHz base frequency, up to 4.6 GHz with Intel[®] Turbo Boost Technology, X MB cache, 6 cores)^{1,2,3,4,5,6}

11th Generation Intel[®] Core[™] i5 11400H with Intel[®] Iris[®] Xe Graphics (2.7 GHz base frequency, up to 4.5 GHz with Intel[®] Turbo Boost Technology, X MB cache, 6 cores) ^{1,2,3,4,5,6}

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode. ³ Intel[®] Turbo Boost performance varies depending on hardware, software and overall system configuration. Energy Efficient Turbo is a power management feature that can lower the maximum core ratio (frequency), if the CPU thinks it can achieve about the same performance as with the maximum turbo frequency. Energy Efficient Turbo feature is disabled in Comet Lake H in order to prioritize performance in DC mode. It can be changed in F10 BIOS settings. See www.intel.com/technology/turboboost for more information.



Features

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

⁵ For full Intel[®] vPro[®] functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See http://intel.com/vpro

⁶Intel[®] Iris[®] Xe Graphics capabilities require system to be configured with Intel[®] Core[™] i5 or i7 processors and dual channel memory. Intel[®] Iris[®] Xe Graphics with Intel[®] Core[™] i5 or 7 processors and single channel memory will only function as UHD graphics.



Features

CHIPSET

Mobile Intel[®] TigerLake PCH-H, WM 590

INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO TECHNOLOGY CAPABLE

Intel[®] Core[™] i5 with vPro[®], Core[™] i7 with vPro[®] and Core[™] i9 with vPro[®] technology is a selectable feature that is available on units configured with select processors, a qualified Intel[®] WLAN module and a preinstalled Windows[®] operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel[®] Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state. ^{1,2}

¹ Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

² For full Intel[®] vPro[®] functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See http://intel.com/vpro

GRAPHICS

Integrated Intel® Iris® Xe Graphics ^{1,2,3,4,5} Discrete NVIDIA Graphic options: NVIDIA RTX™ A2000 (4 GB GDDR6 dedicated) ^{1,2,3,4,5} NVIDIA® T1200 (4 GB GDDR6 dedicated) ^{1,2,3,4,5} NVIDIA® T600 (4 GB GDDR dedicated) ^{1,2,3,4,5}

¹ UHD content required to view UHD images.

² Support HD decode, DX11, DX12, HDMI 1.4, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 30Hz

³ HDMI cable Sold Separately

⁴ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.
 ⁵ GPU configurations may be limited to specific panel options

Multi Display Support

With HP Thunderbolt™ Dock G2

HP ZBook Power configuration with hybrid graphics supports a maximum of three independent displays which can include any combination of the Internal panel and two external display connected to the HDMI port and/or external displays connected to the dock Type-C[®], or VGA, or two DisplayPort[™] ports.

NOTE: Resolutions are dependent upon monitor capability and resolution and color depth settings.



Features

Without HP Thunderbolt™ Dock G2

HP ZBook Power with hybrid graphics and without the use of the dock supports up to a maximum of three independent displays, Internal panel plus two external displays connected to the two following ports: HDMI 2.0, Thunderbolt™ 4

NOTE: Resolutions are dependent upon monitor capability and resolution and color depth settings.

DISPLAY

Non-touch

- 15.6" diagonal FHD IPS eDP1.2 anti-glare bent WLED-backlit and ambient light sensor 250 nits 45% NTSC (1920 x 1080)
- 15.6" diagonal FHD Low Power IPS eDP1.4 + PSR2 anti-glare bent WLED-backlit and ambient light sensor 400 nits 100% sRGB (1920 x 1080)^{1,2}
- 15.6" diagonal UHD Low Power IPS eDP 1.4 + PSR2 +PSR anti-glare bent WLED-backlit and ambient light sensor 400 nits 100% sRGB (3840 x 2160)^{1,2}

Touch

 15.6" diagonal FHD IPS eDP1.2 anti-glare bent WLED-backlit Touch On Cell screen with ambient light sensor 250 nits 45% NTSC (1920 x 1080)^{1,2,3}

¹ UHD content required to view UHD images.

² Resolutions are dependent upon monitor capability, and resolution and color depth settings.

³Actual brightness will be lower with Sure View or touchscreen.



Features

STORAGE AND DRIVES*

Max Storage 4TB through two M.2 NVMe drives

(up to 2) M.2 Storage (NVMe[™] PCIe SSD) 256 GB PCIe[®] NVMe[™] M.2 SSD 512 GB PCIe[®] NVMe[™] M.2 SSD 1 TB PCIe[®] NVMe[™] M.2 SSD 2 TB PCIe[®] NVMe[™] M.2 SSD 256 GB PCIe[®] NVMe[™] M.2 SED SSD 512 GB PCIe[®] NVMe[™] M.2 SED SSD

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe) Primary slot M.2 Storage Bay (PCIe NVMe) Secondary slot RAID: Up to PCIe Gen 4 x 4 lanes NVMe Solid State Drive PCIe Gen 3 x 4 lanes NVMe Solid State Drive RAID 0/1

MEMORY

Maximum Memory¹ 64 GB DDR4-3200 non-ECC SDRAM² 2 DDR4 SODIMMS⁴ Supports Dual Channel Memory³ Slots are customer accessible / upgradeable

¹ Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed. ²Transfer rates up to 3200 MT/s on nECC memory.

³ Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

⁴ Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.



Features

NETWORKING/COMMUNICATIONS

LAN

Intel[®] I219-LM GbE, vPro[®] Intel[®] I219-V GbE, non-vPro[®]

¹GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

WLAN

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5.2 combo, vPro^{® 1} Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5.2 combo, non-vPro^{® 1}

¹ Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

Optional Near Field Communication (NFC) module

AUDIO/MULTIMEDIA

Audio

HP Audio, dual stereo speakers, dual array digital microphone³, functions keys for volume up and down, combo microphone/headphone jack, HD audio

Camera^{1, 2} 720p HD webcam with IR 720p HD webcam

¹ HD content required to view HD images respectively.

² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.
³Dual-microphone array when equipped with optional webcam.



Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Quiet Keyboard, full-size, spill-resistant, backlit, with Programmable Key, with sperate numeric keypad, clickpad with glass surface, multi-touch gestures and taps enabled

Pointing Devices

Clickpad with multi-touch gestures enabled, taps enabled as default; Microsoft Precision Touchpad Default Gestures Support

SOFTWARE AND SECURITY

Workstation ISV Certifications

See the latest list of certifications at: http://www.hp.com/go/isv

HP ZCENTRAL REMOTE BOOST SOFTWARE

The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS

HP Performance Advisor

HP Performance Advisor HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements. Download at: https://www.hp.com/us-en/workstations/performance-advisor.html

Software

Adobe Creative Cloud Bundle Bing search for IE11: **Buv Office: Data Science Stack** HP Connection Optimizer¹ HP Cloud Recovery² **HP Easy Clean HP PC Hardware Diagnostics HP Privacy Settings** HP Hotkey Support; HP Noise Cancellation Software; HP Performance Advisor²⁰ HP QuickDrop³ HP Remote Graphics Software; HP Smart Support⁴ HP Support Assistant; HP ZCentral Remote Boost 2020 Software for Z workstation⁵ TileApp

Manageability Features

HP Driver Packs (download) HP Manageability Integration Kit Gen4 (download)⁶ HP Client Catalog (download) HP Client Management Script Library (download) HP Image Assistant (download)

Security Management

HP Pro Security Edition (optional)⁷ HP Client Security Manager Gen7 HP Sure Sense⁸

Features

HP Sure Click⁹ HP Sure Run Gen4¹⁰ HP Sure Recover Gen4¹¹ HP Sure Start Gen6¹² HP Sure Admin¹³ HP BIOSphere Gen6¹⁴ HP Secure Erase¹⁵ Absolute Persistence Module¹⁶ HP Drive Lock & Automatic Drive Lock¹⁷ BIOS Update via Network HP Wake on WLAN TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)¹⁸ HP Fingerprint Sensor Secured-Core PC Enable¹⁹ HP Tamper Lock

BIOS Version

ISO/IEC 19678: 2015 (formerly NIST 800-147) compliant UEFI version: 2.7

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

¹ HP Connection Optimizer requires Windows 10.

² HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel[®] or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630

³ HP QuickDrop requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.

⁴ HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

⁵ HP ZCentral Remote Boost Sender does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase through 2022. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. ZCentral Remote Boost Sender for non-Z Hardware requires a license and Windows 10, RHEL/CentOS (7 or 8), or UBUNTU 18.04 or 20.04 LTS operating systems. macOS (10.14 or newer) operating system and ThinPro 7.2 are only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.

⁶ HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.

⁷ HP Wolf Pro Security Edition (including HP Sure Click Pro and HP Sure Sense Pro) is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-

en/document/c00581401?openCLC=true as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either <u>a</u> twelve (12) <u>month</u> or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support."

⁸ HP Sure Sense is available on select HP PCs and is not available with Windows10 Home.

⁹ HP Sure Click requires Windows 10. See https://bit.ly/2PrLT6A_SureClick for complete details.

¹⁰ HP Sure Run Gen4 is available on select HP PCs and requires Windows 10.

¹¹ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.

¹² HP Sure Start Gen6 is available on select HP PCs.

Features

¹³ HP Sure Admin requires HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

¹⁴ HP BIOSphere Gen6 features may vary depending on the platform and configuration.

¹⁵ For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] Optane[™].

¹⁶ Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/. ¹⁷Drive Lock is not supported on NVMe drives

¹⁸ TPM 2.0 is limited on HP ThinPro/HP Smart Zero, and functionality is dependent upon use of a customer-enabled application that can locate the TPM chip.

¹⁹ Secured-Core PC Enable only available with vPro config and with TPM)

²⁰HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: https://www.hp.com/us-en/workstations/performance-advisor.html



Features

POWER

Power Supply

Up to 12 hours¹

HP Long Life 6-cell, 83 Wh Li-ion polymer^{2,5}

120 W Slim Smart external AC power adapter³ 150 W Slim Smart external AC power adapter⁴

Supports battery fast charge: approximately 50% in 30 minutes (defined under system hibernation and off mode)

¹ Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark18 battery benchmark https://bapco.com/products/mobilemark-2018/ for additional details.
 ² Battery is internal and not replaceable by customer. Serviceable by warranty. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year.

³Only available with UMA graphics

⁴ Only available with discrete graphic options

⁵Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

ENVIRONMENTAL

Targeting ENERGY STAR[®] certified and EPEAT[®] GOLD registered configurations available ¹

Low halogen²

¹ Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit www.epeat.net for more information.

² External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.



Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h) 35.94 x 23.39 x 2.28 cm 14.15 x 9.21 x 0.9 in

Weights

Starting at 1.9kg (4.16 lb) Weight varies by configuration and components.

A deck: Anodized Aluminum B deck: PC-ABS with Talc C deck: Anodized Aluminum D deck: Anodized Aluminum Metal Alloy Hinges

PORTS/SLOTS

Left side

1 RJ-45 1 SuperSpeed USB Type-A 5Gbps signaling rate (charging) [USB 3.1 Gen 1 Type A charging] 1 HDMI^{1,2} 1 smart card reader 1 Nano Security Lock Slot

Right side

1 power connector 1 Audio Combo Jack 1 USB Type-C® (Thunderbolt™ 4, pass through support DisplayPort™ 1.4, USB 3.1 Gen 2, with BC 1.2) 2 SuperSpeed USB Type-A 5Gbps signaling rate [USB 3.1 Gen 1 Type A]

¹HDMI port-cable not included. ²HDMI 2.0 with discrete, 1.4 with UMA.

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services¹ are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

¹ HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP Services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Nominal Operating 19.5V Requirements (AC Power) Average Operating 2.5W System in idle mode + max Adapter Safety test panel brightness Power(idle) 2.5W System in idle mode + max Adapter Safety test condition Discrete Graphics NVIDIA® T600: 25W panel brightness condition NUDIA® T1200: Max-Q 35W NVIDIA® T1200: Max-Q 35W NVIDIA® T1200: Max-Q 35W Max Operating Power <150W NVIDIA® T1200: Max-Q 35W Max Operating Power 2° to 95° F (0° to 35° C) (No sustained direct exposure to sunlight.) Non-operating 2° to 95% (101.6° F (-20° to 60° C) Relative Humidity Operating 10% to 90%, non-condensing Non-operating 5% to 95% (101.6° F (38.7° C) maximum wet bulb temperature, non-condensing Shock Operating 240 G, 2 ms, half-sine Random Vibration Operating Nominal 1.043 grms Non-operating Nominal 3.50 grms Non-operating Maximum Altitude Operating 10,000 ft (3,048 m) (unpressurized) Operating 1.8°F / 1000 ft (1°C / 3U-8 m) Temperature Derating with Operating 1.8°F / 1000 ft (1°C / 3U-8 m) Planned
Power(idle) panel brightness condition Discrete Graphics NVIDIA® T600: 25W NVIDIA RTX™ A2000: Max-Q 35W NVIDIA RTX™ A2000: Max-Q 35W Max Operating Power <150W Temperature Operating 32° to 95° F (0° to 35° C) (No sustained direct exposure to sunlight.) Non-operating Relative Humidity Operating -4° to 140° F (-20° to 60° C) Relative Humidity Operating 10% to 90%, non-condensing Non-operating 5% to 95% (101.6° F (38.7° C) maximum wet bulb temperature, non-condensing) Shock Operating 240 G, 2 ms, half-sine Non-operating 240 G, 2 ms, half-sine Random Vibration Operating Nomial 3.50 grms Maximum Altitude (unpressurized) Operating 10,000 ft (3,048 m) Non-operating 10,000 ft (12,192 m) Image: State
NVIDIA® T1200: Max-Q 35W NVIDIA RTX™ A2000: Max-Q 35WMax Operating Powee<150WTemperatureOperating32° to 95° F (0° to 35° C) (No sustained direct exposure to sunlight.) Mon-operatingRelative HumidityOperating-4° to 140° F (-20° to 60° C)Relative HumidityOperating10% to 90%, non-condensingNon-operatingS% to 95% (101.6° F (38.7° C) maximum wet bulb temperature, non-condensing)ShockOperating40 G, 2 ms, half-sineNon-operating240 G, 2 ms, half-sineNon-operatingNomial 1.043 grmsNon-operatingNon-operatingNon-operatingNomial 3.50 grmsMaximum AltitudeOperatingNon-operating10,000 ft (12,192 m)Maximum AltitudeOperatingNon-operating1.8°F / 1000 ft (1°C / 304.8 m)Planned Industry StandardULCSAYesFCC complianceYesFCC SAYesFCC SAYesFERGY STAR®Yes²
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Non-operating5% to 95% (101.6° F (38.7° C) maximum wet bulb temperature, non-condensing)ShockOperating40 G, 2 ms, half-sineNon-operating240 G, 2 ms, half-sineRandom VibrationOperatingNominal 1.043 grmsNon-operatingNominal 3.50 grmsMaximum Altitude (unpressurized)Operating10,000 ft (3,048 m)Non-operating40,000 ft (12,192 m)Temperature Derating with AltitudeOperating1.8°F / 1000 ft (1°C / 304.8 m)Planned Industry Standard CertificationsULYesFCC Compliance ENERGY STAR® EPEAT®YesENERGY STAR® EPEAT®Yes2
ShockOperating40 G, 2 ms, half-sineNon-operating240 G, 2 ms, half-sineRandom VibrationOperatingNominal 1.043 grmsMaximum Altitude (unpressurized)Operating10,000 ft (3,048 m)Non-operating40,000 ft (12,192 m)Temperature Derating with AltitudeOperating1.8°F / 1000 ft (1°C / 304.8 m)Planned Industry Standard CertificationsULYesFCC Compliance ENERGY STAR® EPEAT®YesENERGY STAR® EPEAT®Yes2
Non-operating240 G, 2 ms, half-sineRandom VibrationOperatingNominal 1.043 grmsNon-operatingNominal 3.50 grmsMaximum Altitude (unpressurized)Operating10,000 ft (3,048 m)Non-operating40,000 ft (12,192 m)Temperature Derating with AltitudeOperating1.8°F / 1000 ft (1°C / 304.8 m)Planned Industry Standard CertificationsULYesFCC Compliance ENERGY STAR® EPEAT®YesENERGY STAR® EPEAT®Yes2
Random VibrationOperatingNominal 1.043 grmsNon-operatingNominal 3.50 grmsMaximum Altitude (unpressurized)Operating10,000 ft (3,048 m)Non-operating40,000 ft (12,192 m)Temperature Derating with AltitudeOperating1.8°F / 1000 ft (1°C / 304.8 m)Planned Industry Standard CertificationsULYesFCC Compliance ENERGY STAR® EPEAT®Yes2
Non-operatingNominal 3.50 grmsMaximum Altitude (unpressurized)Operating10,000 ft (3,048 m)Non-operating40,000 ft (12,192 m)Temperature Derating with AltitudeOperating1.8°F / 1000 ft (1°C / 304.8 m)Planned Industry Standard CertificationsULYesCERGY STAR® EPEAT®Yes2
Maximum Altitude (unpressurized)Operating Non-operating10,000 ft (3,048 m) 40,000 ft (12,192 m)Temperature Derating with AltitudeOperating1.8°F / 1000 ft (1°C / 304.8 m)Planned Industry Standard CertificationsULYesCSAYesFCC Compliance ENERGY STAR® EPEAT®Yes2
(unpressurized)Non-operating40,000 ft (12,192 m)Temperature Derating with AltitudeOperating1.8°F / 1000 ft (1°C / 304.8 m)Planned Industry Standard CertificationsULYesCSAYesFCC Compliance ENERGY STAR® EPEAT®YesEPEAT®Yes²
Temperature Derating with AltitudeOperating1.8°F / 1000 ft (1°C / 304.8 m)Planned Industry Standard CertificationsULYesCSAYesFCC Compliance ENERGY STAR® EPEAT®YesEPEAT®Yes²
Altitude Ves Planned Industry Standard UL Yes Certifications CSA Yes FCC Compliance Yes ENERGY STAR® Yes EPEAT® Yes ²
Certifications CSA Yes FCC Compliance Yes ENERGY STAR® Yes EPEAT® Yes ²
FCC Compliance Yes ENERGY STAR® Yes EPEAT® Yes ²
ENERGY STAR® Yes EPEAT® Yes ²
EPEAT® Yes ²
ICES Yes
Australia / NZ A-Tick Yes Compliance
CCC Yes
Japan VCCI Compliance Yes
KCC Yes
BSMI Yes
CE Marking Compliance Yes
MIL STD 810H Yes
BNCI or BELUS Yes
GOST Yes
Saudi Arabian
Compliance (ICCP) Yes
UKRSERTCOMPUTER Yes

¹Configurations of the HP ZBook Power 15.6 Inch G8 Mobile Workstation that are ENERGY STAR[®] qualified are identified as HP ZBook Power 15.6 Inch G8 Mobile Workstation ENERGY STAR on HP websites and on http://www.energystar.gov. ²Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit www.epeat.net for more information.



Technical Specifications – System Unit

Technical Specifications – Displays

DISPLAYS

15.6" diagonal FHD IPS eDP anti-glare bent WLED-backlit and ambient light sensor 250 nits 45% NTSC (1920 x 1080) NWBZ

Outline Dimensions (W x H)	350.96 x 205.54 mm (max)	
Active Area	344.16 x 193.59 mm (typ.)		
Weight	370 g (max)		
-	15.6 inch		
Diagonal Size			
Thickness	3.0 mm/ 5.0 mm (w/P	CB) (max)	
Interface	eDP 1.2 (2 lane)		
Panel Technology	IPS		
Surface Treatment	Anti-Glare		
Touch Enabled	No		
Contrast Ratio	600:1 (typ.)		
Refresh Rate	60 hz		
Brightness	250 nits		
Pixel Resolution	Format	1920 x 1080 (FHD)	
	Configuration	RGB Stripe	
Backlight	LED		
PPI	142		
Color Gamut Coverage	NTSC 45%		
Color Depth	6 bits (Hi FRC supportive w/ condition to enable)		
Viewing Angle	UWVA 85/85/85/85		

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

15.6" diagonal FHD Low Power IPS eDP1.4 antiglare bent WLED-backlit and ambient light sensor 400 nits low power 100% sRGB (1920 x 1080)

Outline Dimensions (W x H)	349.46 x 204.79 mm (max)	
Active Area	344.16 x 193.59 mm (typ.)	
Weight	325 g (max)	
Diagonal Size	15.6 inch	
Thickness	2.6mm / 4.6mm (PCB) (max)	
Interface	eDP 1.4 (2 lane)	
Panel Technology	IPS	
Surface Treatment	Anti-Glare	
Touch Enabled	No	
Contrast Ratio	1200:1 (typ.)	
Refresh Rate	60 Hz	
Brightness	400 nits	
Pixel Resolution	Format	1920 x 1080 (FHD)
	Configuration	RGB Stripe
Backlight	LED	
PPI	166	
Color Gamut Coverage	sRGB 100%	
Color Depth	8 bit	
Viewing Angle	UWVA 85/85/85/85	



Technical Specifications – Displays

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

15.6" diagonal UHD Low
Power IPS eDP1.4 +PSR
anti-glare bent WLED-
backlit and ambient light
sensor 400 nits 100%
sRGB (3840 x 2160)

Outline Dimensions (W x H)	349.52 x 205.42 mm (max)
Active Area	344.22 x 193.62 mm (typ.)	
Weight	320 g (max)	
Diagonal Size	15.6"	
Thickness	2.6mm / 4.6mm (PCB)	(max)
Interface	eDP 1.4 (2 lane)	
Panel Technology	IPS	
Surface Treatment	Anti-glare (AG)	
Touch Enabled	No	
Contrast Ratio	1200:1 (typ.)	
Refresh Rate	60Hz	
Brightness	400nits	
Pixel Resolution	Format	3840x2160 (UHD)
Backlight	LED	
PPI	282	
Color Gamut Coverage	100% sRGB	
Color Depth	8 bits	
Viewing Angle	UWVA 85/85/85/85	

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

15.6" diagonal FHD IPS
eDP anti-glare bent
WLED-backlit Touch On
Panel screen with
Corning [®] Gorilla [®] Glass 5
with ambient light sensor
250 nits 45% NTSC (1920
x 1080)

Outline Dimensions (W x H)	350.96 x 205.74 mm ((may)	
	···· ·· ·· · · · · · · · · · · · · · ·		
Active Area	344.16 x 193.59 mm (typ.)		
Weight	380 g (max)		
Diagonal Size	15.6 inch		
Thickness	3.2mm/ 5.2mm (PCB)	(max)	
Interface	eDP 1.2 (2 lane)		
Panel Technology	IPS		
Surface Treatment	Anti-Glare On-cell		
Touch Enabled	Yes		
Contrast Ratio	600:1 (typ.)		
Refresh Rate	60 Hz		
Brightness	250 nits*		
Pixel Resolution	Format	1920 x 1080 (FHD)	
	Configuration	RGB Stripe	
Backlight	LED		
PPI	142		
Color Gamut Coverage	NTSC 45%		
Color Depth	6 bits		
Viewing Angle	UWVA 85/85/85/85		
	and the second second second		

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Displays

*Actual brightness will be lower with Sure View or touchscreen.



Technical Specifications – Storage

STORAGE AND DRIVES

STORAGE AND DIAN				
256GB PCIe NVMe TLC M.2		M.2 2280		
2280 Solid State Drive	Drive Weight	0.02 lb (10 g)		
	Capacity	256GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3500 MB/s	2200 MB/s	
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [amb	ient temp]	
	Features	ATA Security; TRIM; L1.2		
		formatted capacity is less. Up system recovery software.	on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for eeds, slot 2 supports up to Gen 3 speeds	
256GB PCIe NVMe TLC M.2	Form Factor	M.2 2280		
2280 SED Opal 2 Solid	Drive Weight	0.02 lb (10 g)		
State Drive	Capacity	256 GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Interface Performance	PCIe NVMe Gen3X4 Maximum Sequential Read	Maximum Sequential Write	
			Maximum Sequential Write 2200 MB/s	
		Maximum Sequential Read		
	Performance	Maximum Sequential Read 3500 MB/s	2200 MB/s	
	Performance Logical Blocks	Maximum Sequential Read 3500 MB/s 500,118,192	2200 MB/s	
	Performance Logical Blocks Operating Temperature	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up to system recovery software.	2200 MB/s	
512GB PCle NVMe TLC M.2	Performance Logical Blocks Operating Temperature Features	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up to system recovery software.	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for	
512GB PCIe NVMe TLC M.2 2280 Solid State Drive	Performance Logical Blocks Operating Temperature Features	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up f system recovery software. Slot 1 supports up to Gen 4 spe	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for	
	Performance Logical Blocks Operating Temperature Features Form Factor	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up to system recovery software. Slot 1 supports up to Gen 4 spe M.2 2280	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for	
	Performance Logical Blocks Operating Temperature Features Form Factor Drive Weight	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up to system recovery software. Slot 1 supports up to Gen 4 spe M.2 2280 0.02 lb (10 g)	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for	
	Performance Logical Blocks Operating Temperature Features Form Factor Drive Weight Capacity	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up f system recovery software. Slot 1 supports up to Gen 4 spo M.2 2280 0.02 lb (10 g) 512GB	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for	
	Performance Logical Blocks Operating Temperature Features Form Factor Drive Weight Capacity NAND Type	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up to system recovery software. Slot 1 supports up to Gen 4 spo M.2 2280 0.02 lb (10 g) 512GB TLC	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for	
	Performance Logical Blocks Operating Temperature Features Form Factor Drive Weight Capacity NAND Type Height	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up f system recovery software. Slot 1 supports up to Gen 4 spo M.2 2280 0.02 lb (10 g) 512GB TLC 0.09 in (2.3 mm)	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for	
	Performance Logical Blocks Operating Temperature Features Form Factor Drive Weight Capacity NAND Type Height Width	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up to system recovery software. Slot 1 supports up to Gen 4 spo M.2 2280 0.02 lb (10 g) 512GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm)	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for	
	Performance Logical Blocks Operating Temperature Features Form Factor Drive Weight Capacity NAND Type Height Width Interface	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up f system recovery software. Slot 1 supports up to Gen 4 spe M.2 2280 0.02 lb (10 g) 512GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for eeds, slot 2 supports up to Gen 3 speeds	
	Performance Logical Blocks Operating Temperature Features Form Factor Drive Weight Capacity NAND Type Height Width Interface	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up f system recovery software. Slot 1 supports up to Gen 4 spo M.2 2280 0.02 lb (10 g) 512GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Maximum Sequential Read	2200 MB/s Tent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for teeds, slot 2 supports up to Gen 3 speeds Maximum Sequential Write	
	Performance Logical Blocks Operating Temperature Features Form Factor Drive Weight Capacity NAND Type Height Width Interface Performance	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up for system recovery software. Slot 1 supports up to Gen 4 spon M.2 2280 0.02 lb (10 g) 512GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Maximum Sequential Read 3500 MB/s	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for eeds, slot 2 supports up to Gen 3 speeds Maximum Sequential Write 2956 MB/s	
	Performance Logical Blocks Operating Temperature Features Form Factor Drive Weight Capacity NAND Type Height Width Interface Performance Logical Blocks	Maximum Sequential Read 3500 MB/s 500,118,192 32° to 158°F (0° to 70°C) [ambi ATA Security (Option); TCG Opa For storage drives, GB = 1 billio formatted capacity is less. Up f system recovery software. Slot 1 supports up to Gen 4 spo M.2 2280 0.02 lb (10 g) 512GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Maximum Sequential Read 3500 MB/s 1,000,215,215	2200 MB/s ent temp] al 2.0; TRIM; L1.2 on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for eeds, slot 2 supports up to Gen 3 speeds Maximum Sequential Write 2956 MB/s	



Technical Specifications – Storage

512TB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive	Form Factor Drive Weight Capacity NAND Type Height Width Interface	formatted capacity is less. Up system recovery software.	on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for eeds, slot 2 supports up to Gen 3 speeds	
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3500 MB/s	2956 MB/s	
	Logical Blocks	1,000,215,215		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambi	ient temp]	
	Features	ATA Security (Option); TCG Opa	al 2.0; TRIM; L1.2	
		formatted capacity is less. Up system recovery software.	on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for eeds, slot 2 supports up to Gen 3 speeds	
1TB PCIe NVMe TLC M.2	Form Factor	M.2 2280		
2280 Solid State Drive	Drive Weight	0.02 lb (10 g)		
	Capacity	1TB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3500 MB/s	3000 MB/s	
	Logical Blocks	2,000,409,264		
	Operating Temperature	32° to 158°F (0° to 70°C) [amb	ient temp]	
	Features	ATA Security; TRIM; L1.2		
		formatted capacity is less. Up system recovery software.	on bytes. TB = 1 trillion bytes. Actual to 30 GB (for Windows 10) is reserved for eeds, slot 2 supports up to Gen 3 speeds	
2TB PCIe NVMe TLC M.2	Form Factor	M.2 2280		
2280 Solid State Drive	Drive Weight	0.02 lb (10 g)		
	Capacity	2TB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3500 MB/s	3000MB/s	
	Logical Blocks	3,907,029,168		

(III)

Technical Specifications – Storage

	Operating Temperature	32° to 158°F (0° to 70°C) [ambie	ent temp]	
	Features	ATA Security (Option);TRIM; L1.2		
		For storage drives, GB = 1 billio formatted capacity is less. Up to system recovery software.	bytes. TB = 1 trillion bytes. Actual o 30 GB (for Windows 10) is reserved for eds, slot 2 supports up to Gen 3 speeds	
512TB PCIe Gen 4 NVMe	Form Factor	M.2 2280		
TLC M.2 2280 Solid State	Drive Weight	0.02 lb (10 g)		
Drive	Capacity	512GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen4X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		6600 MB/s	5100 MB/s	
	Logical Blocks	1,000,215,215		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambie	ent temp]	
	Features	Pyrite 2.0; TRIM; L1.2		
		formatted capacity is less. Up to system recovery software.	n bytes. TB = 1 trillion bytes. Actual o 30 GB (for Windows 10) is reserved for eds, slot 2 supports up to Gen 3 speeds	
1TB PCIe Gen 4 NVMe TLC		M.2 2280		
M.2 2280 Solid State Drive	Drive Weight	0.02 lb (10 g)		
	Capacity	1TB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen4X4		
	Performance	Maximum Sequential Read 7100 MB/s	Maximum Sequential Write 5200 MB/s	
	Logical Blocks	2,000,409,264		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambie	ent temp]	
	Features	Pyrite 2.0; TRIM; L1.2		
		formatted capacity is less. Up to system recovery software.	n bytes. TB = 1 trillion bytes. Actual o 30 GB (for Windows 10) is reserved for eds, slot 2 supports up to Gen 3 speeds	
2TB PCIe Gen 4 NVMe TLC		M.2 2280		
M.2 2280 Solid State Drive	Drive Weight	0.02 lb (10 g)		
	Capacity	2TB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen4X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	



Technical Specifications – Storage

	7100 MB/s	5200MB/s
Logical Blocks	4,000,797,360	
Operating Temperature	32° to 158°F (0° to 70°C) [ambi	ent temp]
Features	Pyrite 2.0; TRIM; L1.2	
	For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved system recovery software. Slot 1 supports up to Gen 4 speeds, slot 2 supports up to Gen 3 spee	



NETWORKING/COMMUNICATION

Intel i219LM 10/100/1000	Connector	RJ-45
Integrated NIC vPro®	System Interface	PCI(Intel proprietary) + SMBus
	Data Rates Supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling(Hash Mode Only) Jumbo Frame 9K
	Power consumption	Cable Disconnetion: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Management Interface	Auto MDI/MDIX Crossover cable detection
	IT Manageability	Wake-on-LAN from modem standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components
Intel i219v 10/100/1000	Connector	RJ-45
Integrated NIC non-vPro®	System Interface	PCI(Intel proprietary) + SMBus
	Data Rates Supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support



	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) IEEE 802.3i 10BASE-T IEEE 802.3u 100BASE-TX IEEE 802.3ab 1000BAE-T IEEE 802.3bz 2.5GBASE-T
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling(Hash Mode only) Jumbo Frame 9K
Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite

Intel Wi-Fi 6 AX201 + BT5.2 (802.11ax 2x2, non-vPro®, supporting gigabit file transfer speeds*)** non-vPro®	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11d IEEE 802.11h IEEE 802.11h IEEE 802.11h IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz



	• 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA3 certification IEEE 802.11i WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Reguired)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	 802.11b : +18.5dBm minimum 802.11g : +17.5dBm minimum 802.11a : +18.5dBm minimum 802.11a : +18.5dBm minimum 802.11n HT20(2.4GHz) : +15.5dBm minimum 802.11n HT40(2.4GHz) : +14.5dBm minimum 802.11n HT20(5GHz) : +14.5dBm minimum 802.11ac VHT80(5GHz) : +11.5dBm minimum 802.11ac VHT160(5GHz) : +11.5dBm minimum 802.11ax HT40(2.4GHz) : +10dBm minimum 802.11ax VHT160(5GHz) : +10dBm minimum
Power Consumption	 Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity ³	 802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum 802.11ax, MCS11(VHT160): -58.5dBm maximum



5			
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Form Factor		Card with CNVi Interface	
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non- operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio O	ff; LED Off – Radio ON	
HP Integrated Module with Bluetoe	oth 4.0/4.1/4.2/5.0/5.1	Wireless Technology	
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.		
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW		
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management	ETS 300 328, ETS 300 826		
Certifications	Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance		



LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

*GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

*Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

**Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

Intel Wi-Fi 6 AX201 + BT5.2 (802.11ax 2x2,	Wireless LAN Standards	IEEE 802.11a
		IEEE 802.11b
vPro®, supporting gigabit		IEEE 802.11g
file transfer speeds*)**		IEEE 802.11n
vPro®		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11K
		IEEE 802.11v
	Interoperability	Wi-Fi certified
	• •	
	Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz
		• 2.402 – 2.482 GHZ 802.11a/n/ac/ax
		• 4.9 – 4.95 GHz (Japan)
		• 5.15 – 5.25 GHz
		• 5.25 – 5.35 GHz
		• 5.47 – 5.725 GHz
		• 5.825 – 5.850 GHz
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
		• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
		• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
		• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum
	noundion	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM



Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA3 certification IEEE 802.11i WAPI 		
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 complian	t roaming between access points	
Output Power ²	 802.11b : +18.5dBm minimum 802.11g : +17.5dBm minimum 802.11a : +18.5dBm minimum 802.11n HT20(2.4GHz) : +15.5dBm minimum 802.11n HT40(2.4GHz) : +14.5dBm minimum 802.11n HT20(5GHz) : +15.5dBm minimum 802.11n HT40(5GHz) : +14.5dBm minimum 802.11ac VHT80(5GHz) : +11.5dBm minimum 802.11ac VHT160(5GHz) : +11.5dBm minimum 802.11ax HT40(2.4GHz) : +10dBm minimum 802.11ax VHT160(5GHz) : +10dBm minimum 		
Power Consumption	• Idle mode :50 mW (W	mW (WLAN Associated) VLAN unassociated) Modern Standby: 10mW	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode		
Receiver Sensitivity ³	 •802.11b, 1Mbps : -93.5dBm maximum •802.11b, 11Mbps : -84dBm maximum •802.11a/g, 6Mbps : -86dBm maximum •802.11a/g, 54Mbps : -72dBm maximum •802.11n, MCS07 : -67dBm maximum •802.11n, MCS15 : -64dBm maximum •802.11ac, MCS0 : -84dBm maximum •802.11ac, MCS9 : -59dBm maximum •802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum 		
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface		
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	



Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non-	0 to 10,000 ft (3,048 m)	
	operating	0 to 50,000 ft (15,240 m)	
LED Activity		F; LED White – Radio ON	
HP Integrated Module with Bluetoo Frequency Band	2402 to 2480 MHz	5.2 WIRELESS TECHNOLOGY	
Number of Available Channels	Legacy : 0~79 (1 MHz/	(CH)	
Number of Available Channels	BLE : 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power		nent shall operate as a Class II Bluetooth m transmit power of + 9.5 dBm for BR and	
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17	′ mW	
Bluetooth Software Supported Link Topology	Microsoft Windows Bl	uetooth Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management	ETS 300 328, ETS 300 826		
Certifications	Low Voltage Directive IEC950 UL, CSA, and CE Mark		
	or, coa, and cr mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)		
Security & Manageability		with appropriate Intel® chipset components	



*GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

*Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

**Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

NFC (Near Field Communication) module (optional)

Dimensions (L x W x H) Chipset System interface NFC RF standards	Module 25 mm by 1 NPC100 I2C ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 ECMA-320 NFCIP-2	Target and Initia	
NFC Forum Support		, Type3 and Type	4, NFCIP-1 and NFCIP-2
Reader (PCD-VCD) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz ca	ırds	
Card Emulation (PICC- VICC) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B an MIFARE FeliCa	d B'	
Frequency	13.56 MHz		
NFC Modes Supported	Reader/Writer, Peer-to-Peer		
Raw RF Data Rates	106, 212, 424, 848	kbps	
Operating temperature	0°C to 70°C		
Storage temperature	-20°C to 125°C		
Humidity	10-90% operating 5-95% non-operati	ing	
Supply Operating			
voltage	4.35 to 5.25 Volts		
I/O Voltage	1.8V or 3.3V		
Power Consumption	Booster enable, VCC_BOOST = 5V) Mode Power Consumption,	VBAT= 3.3V, Polling Detected Test Tag Type 1	7.3 mA Total 283.8 mA Net Module 236.8 mA



Technical Specifications – Networking

	Typical	Detected Test Tag Type 2	Total 288.8 mA Net Module 241.8 mA
		Detected Test Tag Type 3	Total 287.7 mA Net Module 240.7 mA
		Detected Test Tag Type 4	Total 282.3 mA Net Module 235.3 mA
Intenna	Antenna connec external to mod	•	connector FPC. Antenna matching is

An



Technical Specifications – Power

POWER

120 Watt Slim Smart AC	Dimensions	138x68.5x25.4mm		
Adapter	Weight	unit: 350g +/- 10g		
	Input	Input Efficiency	88% at 115 Vac and 89% at 230Vac	
		Input frequency range	47 ~ 63 Hz	
		Input AC current	1.7 A at 90 Vac and Maximum Load	
	Output	Output power	120W	
		DC output	19.5V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<18.0A	
	Connector	C5		
	Environmental Design	Operating temperature	32oFto 95oF (Ooto 35oC)	
		Non-operating (storage) temperature	-4oFto 185oF (-20oto 85oC)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	5% to 95%	
		Storage Humidity	5% to 95%	
	EMI and Safety Certifications	 Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class¹ SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 100,000 hours at 25°C ambient condition. 		
	NOTE: Can only be configured with Intel UMA Graphics option			

150 Watt Slim Smart AC	Dimensions	138x66x22mm	
Adapter	Weight	unit: 325g +/- 10g	
	Input	Input Efficiency	88% at 115 Vac and 89% at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	2.7 A at 90 Vac and Maximum Load
	Output	Output power	150W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<16.0A
	Connector	C5	
	Environmental Design	Operating temperature	32oFto 95oF (Ooto 35oC)
		Non-operating (storage) temperature	-4oFto 185oF (-20oto 85oC)
		Altitude	0 to 16,400 ft (0 to 5000m)



Technical Specifications – Power

	Humidity	5% to 95%
	Storage Humidity	5% to 95%
EMI and Safety Certifications	* Worldwide safety sta SELV; Agency approval FCC Class B, CISPR22 C	nce with LVD and EMC directives ndards - IEC60950, EN60950, UL60950, Class1, s - C-UL-US, NORDICS, DENAN, EN55022 Class B, lass B, CCC, NOM-1 NYCE. hours at 25°C ambient condition.
NOTE: Can only be configured with Quadro T1200 and A2000 Graphics option		



Technical Specifications – Power

HP Long Life 6-cell Polymer (83Wh) Battery*			342 x 12.44 x 2.763 inch)	
	Energy	Voltage	11.58V	
		Amp-hour capacity	7.170Ah	
		Watt-hour capacity	83Wh	
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)	
		Operating (Discharging)	14° to 122° F (-10° to 60° C)	
	Fuel Gauge LED	NA		
	Warranty	Refer to http://www.hp.co warranty information.	om/support/batterywarranty/ for battery	
	Optional Travel Battery Available	N/A		
	NOTE: Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform.			
	*Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.			



ENVIRONMENTAL DATA

Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] US Federal Energy Management Program (FEMP) EPEAT[□] Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label* 		
Sustainable Impact Specifications	 Ocean-bound plastic in Speaker Enclosure 15% post-consumer recycled plastic External Power Supply 90% Efficiency Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable Bulk packaging available 		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	6.09 W	6.31 W	5.92 W
Normal Operation (Long idle)	1.43 W	1.41 W	1.47 W
Sleep	1.43 W	1.41 W	1.47 W
Off	0.41 W	0.42 W	0.42 W
	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	21 BTU/hr	21 BTU/hr	21 BTU/hr
Normal Operation (Long idle)	5 BTU/hr	5 BTU/hr	5 BTU/hr
Sleep	5 BTU/hr	5 BTU/hr	5 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.



Declared Noise Emissions		Sound Power	Sound Pressure
(in accordance with ISO 7779 and ISO 9296)	(L _{WAd} , bels)		(L _{DAm} , decibels)
Typically Configured – Idle		2.6	14.3
Fixed Disk – Random writes		3.3	24.3
Optical Drive – Sequential reads		3.6	28.4
Longevity and Upgrading		n be upgraded, possibly exte components contained in th	ending its useful life by several years. Upgradeable e product may include:
	Spare parts are a of production.	available throughout the wa	rranty period and or for up to "5" years after the end
Additional Information	directiv	re - 2011/65/EC.	he Restrictions of Hazardous Substances (RoHS)
	Equipm	nent (WEEE) Directive – 2002	ply with the Waste Electrical and Electronic /96/EC. California Proposition 65 (State of California; Safe
	Drinkin	g Water and Toxic Enforcem	
	www.ej	peat.net	ms used in the product are marked per ISO11469
	and ISO)1043.	
	This pro	oduct is 95.5% recycle-able	when properly disposed of at end of life.
Packaging Materials	External:	PAPER/Corrugated	250 g
Packaying Materials		-	250 g
	Internal:	PAPER/Molded pulp	177 g
		PLASTIC/Polyethylene low	
		kaging material contains at l	-
	-		contains at least 45% recycled content.
RoHS Compliance	RoHS ComplianceHP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.We believe the RoHS directive and similar laws play an important role in promoting industry- wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.		
	To obtain a copy	y of the HP RoHS Compliance	Statement, see HP RoHS position statement.
Material Usage	(refer to the HP	General Specification for the	
):	com/npinto/globalcitizenshi	p/environment/supplychain/gen_specifications.html



- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and
RecyclingHP offers end-of-life HP product return and recycling programs in many geographic areas. To
recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
HP sales office. Products returned to HP will be recycled, recovered or disposed of in a
responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.



Global Citizenship Report
http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
Eco-label certifications
http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
ISO 14001 certificates:
http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
and
http://www.hp.com/hpinfo/qlobalcitizenship/environment/pdf/cert.pdf

footnotes

- Percentage of ocean-bound plastic contained in each component varies by product ٠
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals • excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced • certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials. •



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Displays	HP Z32 31.5" 4k UHD Display	1AA81A8#XXX
	HP Z38c 37.5" Curved Display	Z4W65A8#ABA
Cases	HP 17.3 Business Backpack	2SC67AA
	HP 15.6 Business Top Load	2SC66AA
	HP 17.3 Business Slim Top Load	2UW02AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Executive 17.3 Backpack	6KD05AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 17.3 Top Load	6KD08AA
	HP Executive 15.6 Leather Top Load	6KD09AA
	HP Prelude 15.6 Top Load	1E7D7AA
	HP Prelude 15.6 Backpack	1E7D6AA
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA
	HP Renew Business 17.3 Laptop Bag	3E2U6AA
	HP Renew Business 15.6 Laptop Bag	3E5F8AA
Docking Accessories	HP TB Audio Module (comp with Thunderbolt Dock G2)	3AQ21AA
Docking station	HP USB-C Mini Dock - power not supported on mWKS	1PM64AA
	HP TB Dock G2 w/ Combo Cable (this is 230W)	3TR87AA
	HP USB-C/A Universal Dock G2 Power Not Supported on Mobile Workstations	5TW13AA
	HP USB-C Dock G5 Power Not Supported on Mobile Workstations	5TW10AA
Input/Output -	HP Comfort Grip Wireless Mouse (See Link 5 Tab)	H2L63AA
Mice & Keyboard	HP USB Travel Mouse	G1K28AA
	HP Wireless Premium Mouse (See Link 5 Tab)	1JR31AA
	HP Wired 320M Mouse	9VA80AA
	HP Travel Bluetooth Mouse	6SP30AA
	HP Multi-Device 635 Black Wireless Mouse	1D0K2AA
	HP Creator 935 Black Wireless Mouse	1D0K8AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Wireless (Link-5) Keyboard	T6U20AA
	HP 320K Wired Keyboard	9SR37AA
	HP 125 Wired Keyboard	266C9AA
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
Input/Output -	HDMI to VGA Adapter	H4F02AA
Adapter	HP HDMI to DVI Adapter	F5A28AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA



Options and Accessories (sold separately and availability may vary by country)

	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to VGA Adapter	N9K76AA
	HP USB 3.0 to Gigabit Adapter	N7P47AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
Memory	HP 4GB 3200MHz DDR4 (pending approval)	286H5AA
	HP 8GB 3200MHz DDR4 (pending approval	286H8AA
	HP 16GB 3200MHz DDR4(pending approval)	286J1AA
Power - A/C Adapter	HP 150W Slim Smart 4.5mm AC Adapter	4SC18AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
	HP Sure Key Cable Lock	6UW42AA
Storage - External	HP External USB DVDRW Drive	F2B56AA
Storage – SS M2	HP 256GB PCIe-3x4 NVME M.2 SSD	1D0H6AA
	HP 512GB PCI-e 3x4 NVMe M2 SSD	1D0H7AA



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Date of change:	Version History:		Description of change:
June 29, 2021	From v1 to v2	Changed	AUDIO/MULTIMEDIA section
July 9, 2021	From v2 to v3	Changed	NETWORKING/COMMUNICATIONS section
July 29, 2021	From v3 to v4	Changed	PROCESSOR section
August 11, 2021	From v4 to v5	Changed	SOFTWARE AND SECURITY section
August 18, 2021	From v5 to v6	Changed	Product Name
November 26, 2021	From v6 to v7	Changed	OPERATING SYSTEM section
December 3, 2021	From v7 to v8	Changed	SOFTWARE AND SECURITY section
December 9, 2021	From v8 to v9	Changed	SYSTEM UNIT section
December 15, 2021	From v9 to v10	Changed	OPERATING SYSTEM section
December 23, 2021	From v10 to v11	Changed	NETWORKING/COMMUNICATIONS section

